

			nent mounted on the reverse side of PCB) nent mounted on the reverse side of PCB)	
.5 kVA				
M *4				
depending on the option configuration.)				
th Dual Heads	s) 8-nozzle hea	d (With Dual Heads)	3-nozzle head *6(With Dual Heads)	
058 s/chip) 40 000cp	h(0.090 s/chip)	11 000cph(0.33 s/QFP)	
	±40 μm/ chip ±30 μm/QFP ±50 μm/QFP	□12 mm ~ □32 mm □12 mm Under	\pm 30 μ m /QFP	
2 × W 12 × T 6	6.5 (01005") 0402 chip -	*5 to L 32 × W 32 × T 12	(0201") 0603 chip to L 150 × W 25 (diagonal152) × T 28	
mm	Tape: 8 to 56	/ 72 mm	Tape:8 to 56 / 72 / 88 / 104 mm	
	Single tray speci	ifications : Max.86 (Ta	pe width and feeder are subject to the conditions on the left) pe width and feeder are subject to the conditions on the left) pe width and feeder are subject to the conditions on the left)	
	Single tray speci	specifications:Max.14 ifications:Max.10 fications:Max.7		
		ifications : Max.20 fications : Max.40		
 *5 : The 0402 chip requires a specific nozzle/feeder. *6 : 3-nozzle head is only available to NPM-W and cannot be installed to NPM-D. 				

TION MODULAR NEW PLATFORM



For larger boards and larger components

PCBs up to a size of 750 × 550 mm with component range up to 150 × 25 mm



3 patterns for component supply

With numerous combinations of placement heads and supply methods. coping to issues seen in HMHV manufacturing.



Options for LED Assembly

Brightness uniformity, needed in LED assembly is provided without sacrifice to speed.



Machine Configuration

R: 30 Input Feeders R: Single-Tray R:Twin-Tray 13 fixed bank feeder



F: 30 Input Feeders F: 30 Input Feeders F: 30 Input Feeders *8 & 3 Nozzles head compatible with tray feeding

<Line example (NPM-W \times 3) >



 Feeders : 163 Inputs (326 Inputs when 8mm Double Feeder (S) used)

- Tray: 20 Part Numbers
- Line Throughput : 150,500 cph

• Line Length :4,440 mm



PUCTION MODULAR NPM-W

NEXT





LED Placement	
Brightness Binning	Global
NG	Global Ba
oid mixing of brightness and	Recognition of

Av minimizes component and block disposal. Monitors remaining component

count to avoid component exhaust during operation.

mark recognition. If yes, individual bad mark recognition is performed.

System evolution according to mounting changes

size can be buffered in between machines minimizing board transfer time.